

# DE275X2-501N16A RF Power MOSFET

- ♦ Common Source Push-Pull Pair
- N-Channel Enhancement Mode
- ◆ Low Q<sub>q</sub> and R<sub>q</sub>
- ♦ High dv/dt
- Nanosecond Switching

The DE275X2-501N16A is a matched pair of RF power MOSFET devices in a common source configuration. The device is optimized for push-pull or parallel operation in RF generators and amplifiers at frequencies to >65 MHz.

Unless noted, specifications are for each output device

**Test Conditions** 

Symbol

Symbol	Test Conditions	Maximum Ratings		
V <sub>DSS</sub>	T <sub>J</sub> = 25°C to 150°C	500	V	
$\mathbf{V}_{DGR}$	$T_J$ = 25°C to 150°C; $R_{GS}$ = 1 $M\Omega$	500	V	
V <sub>GS</sub>	Continuous	±20	V	
$V_{GSM}$	Transient	±30	V	
I <sub>D25</sub>	T <sub>c</sub> = 25°C	16	Α	
$I_{DM}$	$T_c$ = 25°C, pulse width limited by $T_{JM}$	96	Α	
I <sub>AR</sub>	$T_c = 25^{\circ}C$	16	Α	
<b>E</b> <sub>AR</sub>	$T_c = 25^{\circ}C$	20	mJ	
dv/dt	$\begin{split} &I_{S} \leq I_{DM}, \; di/dt \leq \tilde{\ } \; 100A/\mu s, \; V_{DD} \leq V_{DSS}, \\ &T_{j} \leq 150^{\circ}C, \; R_{G} = 0.2\Omega \end{split}$	5	V/ns	
	I <sub>S</sub> = 0	>200	V/ns	
<b>P</b> <sub>DHS</sub> (1)	T <sub>c</sub> = 25°C, Derate 6.0W/°C above 25°C	750	W	
P <sub>DAMB</sub> (1)	$T_c = 25^{\circ}C$	5.0	W	
$R_{\text{thJHS}}^{(1)}$		0.17	K/W	
T <sub>J</sub>		-55+150	°C	
$\mathbf{T}_{JM}$		150	°C	
$T_{\text{stg}}$		-55+150	°C	
T <sub>L</sub>	1.6mm (0.063 in) from case for 10 s	300	°C	
Weight		4	g	

	$T_J$ = 25°C unless otherwise specified			
	min.	typ.	max.	
$I_{GS} = 0 \text{ V}, I_D = 3 \text{ ma}$	500			V
$I'_{DS} = V_{GS}$ , $I_D = 4$ ma	2.5		5.5	V
$V_{GS} = \pm 20 \text{ V}_{DC}, \text{ V}_{DS} = 0$			±100	nA
$T_{DS} = 0.8 \text{ V}_{DSS} \text{ T}_{J} = 25^{\circ}\text{C}$ $T_{GS} = 0 \qquad T_{J} = 125^{\circ}\text{C}$			50 1	μA mA
$I_{GS}$ = 15 V, $I_D$ = 0.5 $I_{D25}$ culse test, t $\leq$ 300 $\mu$ S, duty cycle d $\leq$	2%		0.5	Ω
$I_{DS} = 15 \text{ V}, I_{D} = 0.5 I_{D25}, \text{ pulse test}$	2	6		S
,	$I_{DS} = V_{GS}, I_D = 4 \text{ ma}$ $I_{GS} = \pm 20 \text{ V}_{DC}, V_{DS} = 0$ $I_{DS} = 0.8 \text{ V}_{DSS} \text{ T}_J = 25^{\circ}\text{C}$ $I_{GS} = 0 \text{ T}_J = 125^{\circ}\text{C}$ $I_{GS} = 15 \text{ V}, I_D = 0.5I_{D25}$	$I_{GS} = 0 \text{ V}, I_D = 3 \text{ ma}$ 500 $I_{DS} = V_{GS}, I_D = 4 \text{ ma}$ 2.5 $I_{GS} = \pm 20 \text{ V}_{DC}, V_{DS} = 0$ $I_{DS} = 0.8 \text{ V}_{DSS} \text{ T}_J = 25^{\circ}\text{C}$ $I_{GS} = 0 \text{ T}_J = 125^{\circ}\text{C}$ $I_{GS} = 15 \text{ V}, I_D = 0.5I_{D25}$ ulse test, $t \le 300\mu\text{S}$ , duty cycle $d \le 2\%$	$I_{GS} = 0 \text{ V}, I_D = 3 \text{ ma}$ 500 $I_{DS} = V_{GS}, I_D = 4 \text{ ma}$ 2.5 $I_{GS} = \pm 20 \text{ V}_{DC}, V_{DS} = 0$ $I_{DS} = 0.8 \text{ V}_{DSS} \text{ T}_J = 25^{\circ}\text{C}$ $I_{GS} = 0 \text{ T}_J = 125^{\circ}\text{C}$ $I_{GS} = 15 \text{ V}, I_D = 0.5I_{D25}$ ulse test, $t \le 300\mu\text{S}$ , duty cycle $t \le 2\%$	$I_{GS} = 0 \text{ V}, I_D = 3 \text{ ma}$ 500 $I_{DS} = V_{GS}, I_D = 4 \text{ ma}$ 2.5 5.5 $I_{GS} = \pm 20 \text{ V}_{DC}, V_{DS} = 0$ $\pm 100$ $I_{DS} = 0.8 \text{ V}_{DSS} \text{ T}_J = 25^{\circ}\text{C}$ 50 $I_{GS} = 0 \text{ T}_J = 125^{\circ}\text{C}$ 1 $I_{GS} = 15 \text{ V}, I_D = 0.5I_{D25}$ 0.5 ulse test, $t \le 300 \mu\text{S}$ , duty cycle $d \le 2\%$

**Characteristic Values** 

Preliminary Data Sheet

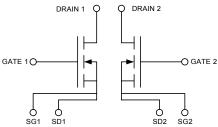
 $V_{DSS} = 500 V$ 

 $I_{D25} = 16 A$ 

 $R_{DS(on)} = 0.5 \Omega$ 

 $P_{DHS} = 750 W$ 





#### **Features**

- Isolated Substrate
- high isolation voltage (>2500V)
- excellent thermal transfer
- Increased temperature and power cycling capability
- IXYS advanced low Q<sub>g</sub> process
- · Low gate charge and capacitances
- easier to drive
- faster switching
- Low R<sub>DS(on)</sub>
- Very low insertion inductance (<2nH)</li>
- No beryllium oxide (BeO) or other hazardous materials

### Advantages

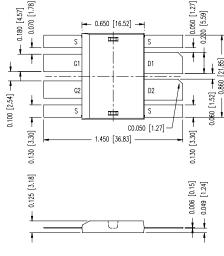
- High Performance Push-Pull RF Package
- Optimized for RF and high speed switching at frequencies to >65MHz
- Easy to mount—no insulators needed
- High power density

Note: All specifications are per each transistor, unless otherwise noted.

(1) Thermal specifications are for the package, not per transistor

Symbol	Test Conditions	Characteristic Values
•		(T. = 25°C unless otherwise sne

	min.	typ.	max.
R <sub>G</sub>		0.3	Ω
Ciss		1800	pF
Coss	$V_{GS} = 0 \text{ V}, V_{DS} = 0.8 \text{ V}_{DSS(max)},$ f = 1 MHz	150	pF
C <sub>rss</sub>		45	pF
$T_{d(on)}$		3	ns
$\mathbf{T}_{on}$	$V_{GS} = 15 \text{ V}, V_{DS} = 0.8 \text{ V}_{DSS}$ $I_D = 0.5 \text{ I}_{DM}$	2	ns
$\mathbf{T}_{d(off)}$	$R_G = 0.2 \Omega$ (External)	4	ns
$T_{off}$		5	ns
<b>Q</b> <sub>g(on)</sub>		50	nC
$\mathbf{Q}_{\mathrm{gs}}$	$V_{GS}$ = 10 V, $V_{DS}$ = 0.5 $V_{DSS}$ $I_D$ = 0.5 $I_{D25}$	20	nC
<b>Q</b> gd		30	nC



# Source-Drain Diode

# **Characteristic Values**

(T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Test Conditions	min.	typ.	max.	
Is	V <sub>GS</sub> = 0 V			16	Α
I <sub>SM</sub>	Repetitive; pulse width limited by $T_{\text{JM}}$			96	Α
V <sub>SD</sub>	$I_F = I_S,  V_{GS} = 0  V,$ Pulse test, $t \leq 300  \mu s,  duty  cycle \leq 2\%$			1.5	V
T <sub>rr</sub>			200		ns
$\mathbf{Q}_{RM}$	$I_F = I_S$ , -di/dt = 100A/ $\mu$ s, $V_R = 100V$		0.8		μС
I <sub>RM</sub>			6.5		Α

<sup>(1)</sup> These parameters apply to the package, not individual MOSFET devices.

For detailed device mounting and installation instructions, see the "*DE-Series MOSFET Mounting Instructions*" technical note on DEI's web site at www.directedenergy.com/apptech.htm

Directed Energy, Inc. reserves the right to change limits, test conditions and dimensions. DEI MOSFETS are covered by one or more of the following U.S. patents:

4,835,592	4,850,072	4,881,106	4,891,686	4,931,844	5,017,508
5,034,796	5,049,961	5,063,307	5,187,117	5,237,481	5,486,715
5.381.025	5.640.045				

#### 501N16A DE-SERIES SPICE Model

The DE-SERIES SPICE Model is illustrated in Figure 1. The model is an expansion of the SPICE level 3 MOSFET model. It includes the stray inductive terms  $L_G$ ,  $L_S$  and  $L_D$ . Rd is the  $R_{DS(ON)}$  of the device, Rds is the resistive leakage term. The output capacitance,  $C_{OSS}$ , and reverse transfer capacitance,  $C_{RSS}$  are modeled with reversed biased diodes. This provides a varactor type response necessary for a high power device model. The turn on delay and the turn off delay are adjusted via Ron and Roff.

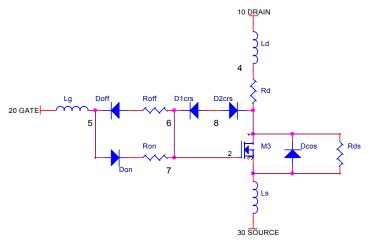


Figure 1 DE-SERIES SPICE Model

This SPICE model may be downloaded as a text file from the DEI web site at www.directedenergy.com/spice.htm

Net List: SYM=POWMOSN .SUBCKT 501N16A 10 20 30 \* TERMINALS: D G S \* 500 Volt 16 Amp .5 ohm N-Channel Power MOSFET \* REVA 6-15-00 M1 12 3 3 DMOS L=1U W=1U RON 56.2 DON 62 D1 ROF 57.2 DOF 27 D1 D1CRS 28 D2 D2CRS 1 8 D2 CGS 23 2.0N RD 41.5 DCOS 3 1 D3 RDS 1 3 5.0MEG LS 330.5N LD 104 1N LG 20 5 1N .MODEL DMOS NMOS (LEVEL=3 VTO=3.0 KP=5.8) .MODEL D1 D (IS=.5F CJO=10P BV=100 M=.5 VJ=.7 TT=1N RS=10M) .MODEL D2 D (IS=.5F CJO=450P BV=500 M=.4 VJ=.6 TT=10N RS=10M) .MODEL D3 D (IS=.5F CJO=900P BV=500 M=.3 VJ=.3 TT=400N RS=10M) .ENDS

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